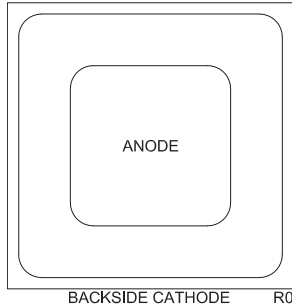


CPD16-CMR1U-06M

Ultra Fast Rectifier Die

1.0 Amp, 600 Volt

The CPD16-CMR1U-06M is a silicon 1.0 Amp, 600 Volt ultra fast recovery rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

| | |
|------------------------|-----------------------|
| Die Size | 50 x 50 MILS |
| Die Thickness | 12.5 MILS |
| Anode Bonding Pad Size | 34 x 34 MILS |
| Top Side Metalization | Ni/Au – 3,000Å/1,350Å |
| Back Side Metalization | Ni/Au – 3,000Å/1,350Å |
| Scribe Alley Width | 3.0 MILS |
| Wafer Diameter | 4 INCHES |
| Gross Die Per Wafer | 4,250 |

MAXIMUM RATINGS: (T_A=25°C)

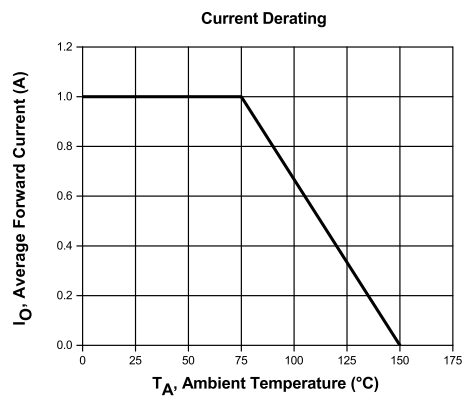
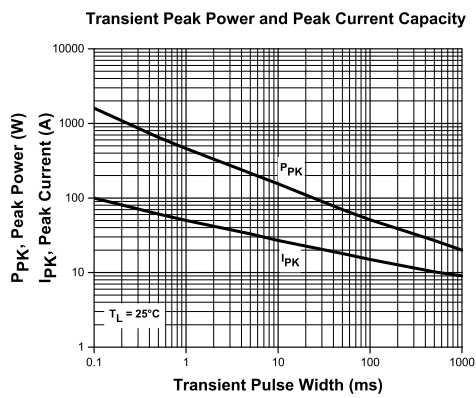
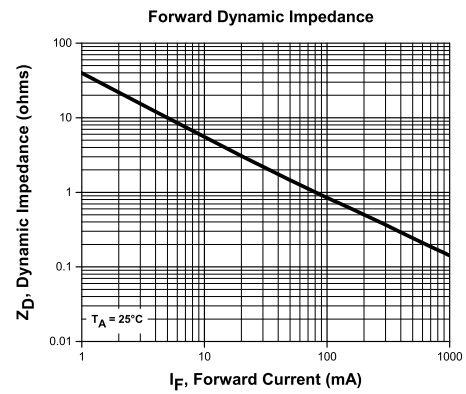
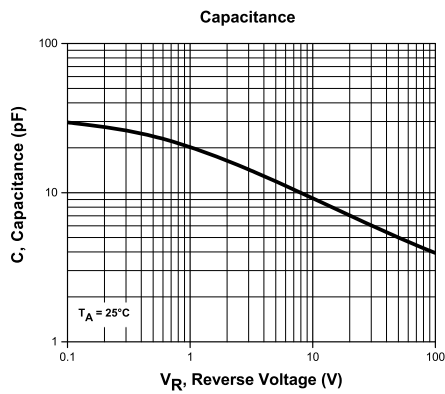
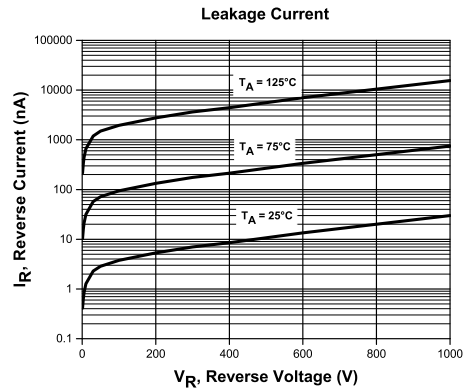
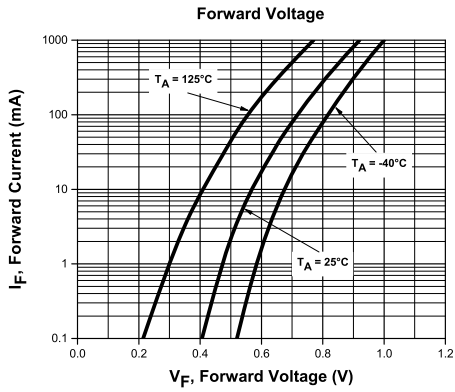
| | SYMBOL | | UNITS |
|--|-----------------------------------|-------------|-------|
| Peak Repetitive Reverse Voltage | V _{RRM} | 600 | V |
| DC Blocking Voltage | V _R | 600 | V |
| RMS Reverse Voltage | V _{R(RMS)} | 420 | V |
| Average Forward Current (T _A =75°C) | I _O | 1.0 | A |
| Peak Forward Surge Current, tp=8.3ms | I _{FSM} | 30 | A |
| Operating and Storage Junction Temperature | T _J , T _{stg} | -65 to +150 | °C |

ELECTRICAL CHARACTERISTICS: (T_A=25°C)

| SYMBOL | TEST CONDITIONS | MIN | MAX | UNITS |
|-----------------|--|-----|-----|-------|
| I _R | V _R =600V | | 5.0 | µA |
| V _F | I _F =1.0A | | 1.4 | V |
| C _J | V _R =0, f=1.0MHz | | 40 | pF |
| t _{rr} | I _F =0.5A, I _R =1.0A, I _{rr} =0.25A | | 75 | ns |

CPD16-CMR1U-06M

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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